

N-Channel Enhancement Mode MOSFET

TDM3512

DESCRIPTION

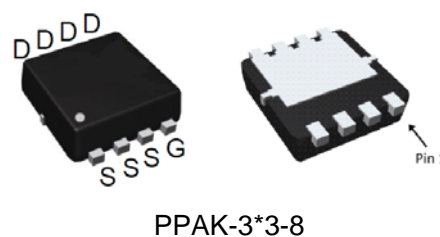
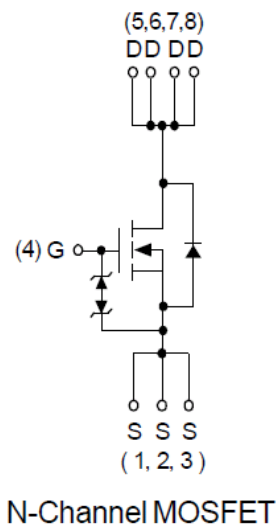
The TDM3512 uses advanced trench technology to provide excellent RDS(ON) and low gate charge. This device is suitable for use as a load switch or in PWM applications.

GENERAL FEATURES

- RDS(ON) < 7mΩ @ VGS=1.8V
RDS(ON) < 4.5mΩ @ VGS=2.5V
RDS(ON) < 3.4mΩ @ VGS=4.5V
- High Power and current handling capability
- Surface Mount Package
- Lead Free and Green Devices available(RoHS Compliant)

Application

- PWM applications
- Load switch
- Power management
- Powered Systems



ABSOLUTE MAXIMUM RATINGS(T_A=25°C unless otherwise noted)

| Parameter | Symbol | Limit | Unit |
|---|--|------------|------|
| Drain-Source Voltage | V _{DS} | 20 | V |
| Gate-Source Voltage | V _{GS} | ±12 | V |
| Diode Continuous Forward Current | I _S (T _C =25°C) | 25 | A |
| Drain Current @ Continuous | I _D (T _C =25°C) | 50 | A |
| | I _D (T _C =100°C) | 40 | A |
| Drain Current @ Current-Pulsed (Note 1) | I _{DM} (T _C =25°C) | 200 | A |
| Maximum Power Dissipation | P _D (T _C =25°C) | 35 | W |
| | P _D (T _C =100°C) | 14 | W |
| Drain Current @ Continuous | I _D (T _A =25°C) | 17.8 | A |
| | I _D (T _A =70°C) | 14.2 | A |
| Maximum Power Dissipation | P _D (T _A =25°C) | 1.6 | W |
| | P _D (T _A =70°C) | 1 | W |
| Thermal Resistance,Junction-to-Case | R _{θJC} | 3.5 | °C/W |
| Thermal Resistance,Junction-to-Ambient (Note 2) | R _{θJA} | 78 | °C/W |
| Maximum Operating Junction Temperature | T _J | 150 | °C |
| Storage Temperature Range | T _{STG} | -55 To 150 | °C |

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ELECTRICAL CHARACTERISTICS ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

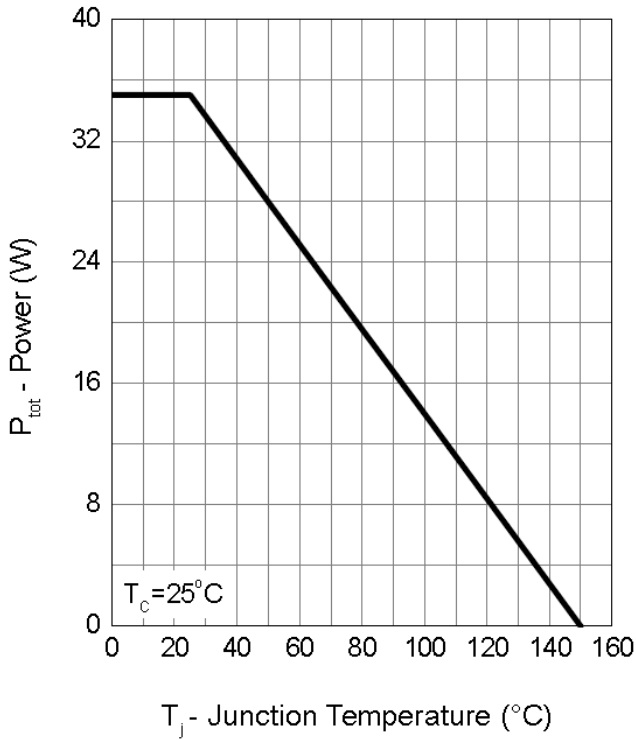
| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|---|--------------|--|-----|------|----------|------------|
| OFF CHARACTERISTICS | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS}=0V, I_D=250\mu A$ | 20 | - | - | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS}=16V, V_{GS}=0V$ | - | - | 1 | μA |
| Gate-Body Leakage Current | I_{GSS} | $V_{GS}=\pm 12V, V_{DS}=0V$ | - | - | ± 10 | μA |
| ON CHARACTERISTICS | | | | | | |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=250\mu A$ | 0.5 | 0.7 | 1 | V |
| Drain-Source On-State Resistance | $R_{DS(on)}$ | $V_{GS}=1.8V, I_D=2A$ | - | 4.6 | 7 | m Ω |
| | | $V_{GS}=2.5V, I_D=10A$ | - | 3.3 | 4.5 | m Ω |
| | | $V_{GS}=4.5V, I_D=13.5A$ | - | 2.7 | 3.4 | m Ω |
| DYNAMIC CHARACTERISTICS (Note3) | | | | | | |
| Gate Resistance | R_G | $V_{DS}=0V, V_{GS}=0V, F=1.0MHz$ | - | 2 | 3.6 | Ω |
| Input Capacitance | C_{iss} | $V_{DS}=10V, V_{GS}=0V, F=1.0MHz$ | - | 3775 | 4910 | PF |
| Output Capacitance | C_{oss} | | - | 730 | - | PF |
| Reverse Transfer Capacitance | C_{rss} | | - | 525 | - | PF |
| SWITCHING CHARACTERISTICS (Note 3) | | | | | | |
| Turn-on Delay Time | $t_{d(on)}$ | $V_{DS}=10V, R_L=10\Omega, V_{GEN}=10V, R_G=6\Omega$ $I_D=1A$ | - | 14 | 26 | nS |
| Turn-on Rise Time | t_r | | - | 14.5 | 27 | nS |
| Turn-Off Delay Time | $t_{d(off)}$ | | - | 130 | 234 | nS |
| Turn-Off Fall Time | t_f | | - | 70 | 126 | nS |
| Total Gate Charge | Q_g | $V_{DS}=10V, I_D=13.5A, V_{GS}=4.5V$ | - | 35 | 50 | nC |
| Gate-Source Charge | Q_{gs} | | - | 4.7 | - | nC |
| Gate-Drain Charge | Q_{gd} | | - | 11.5 | - | nC |
| Body Diode Reverse Recovery Time | T_{rr} | $I_F=13.5A, di/dt=100A/\mu s$ | - | 18 | - | nS |
| Body Diode Reverse Recovery Charge | Q_{rr} | | - | 6.2 | - | nC |
| DRAIN-SOURCE DIODE CHARACTERISTICS | | | | | | |
| Diode Forward Voltage (Note 2) | V_{SD} | $V_{GS}=0V, I_S=2A$ | - | 0.7 | 1.1 | V |

NOTES:

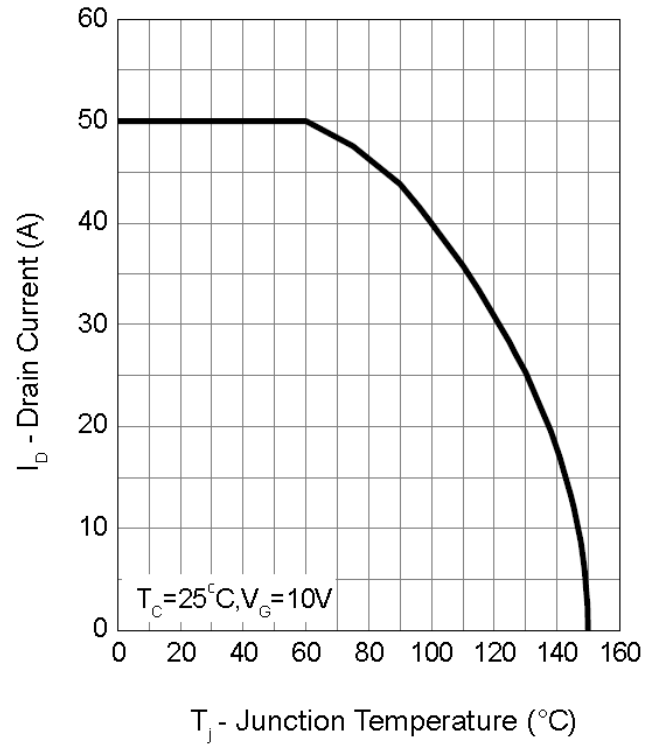
1. Pulse width limited by max. junction temperature.
2. $R_{\theta JA}$ steady state=999s. $R_{\theta JA}$ is measured with the device mounted on 1in2, Fr-4 board with 2oz.Copper
3. Guaranteed by design, not subject to production testing

Typical Operating Characteristics

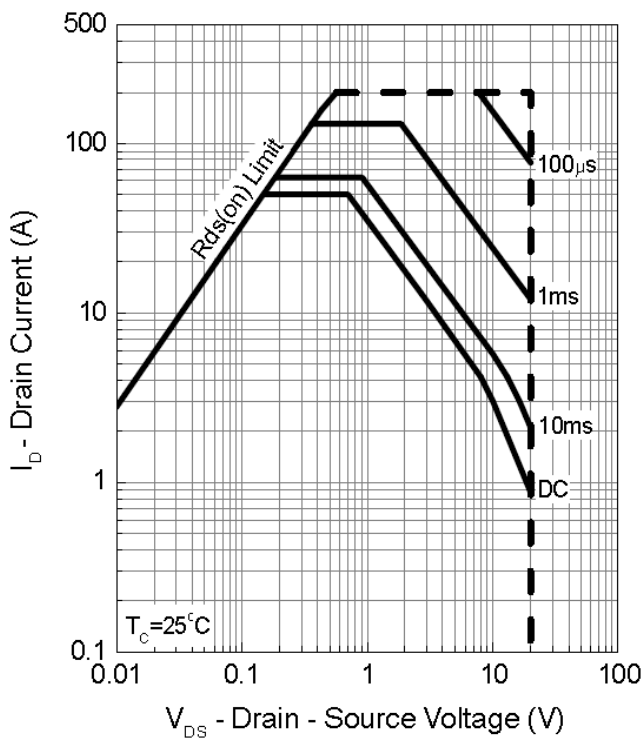
Power Dissipation



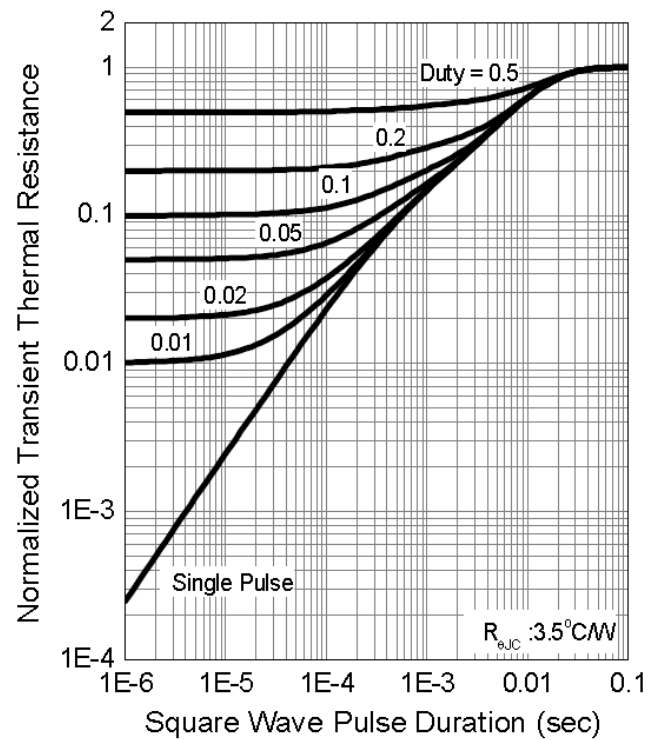
Drain Current



Safe Operation Area

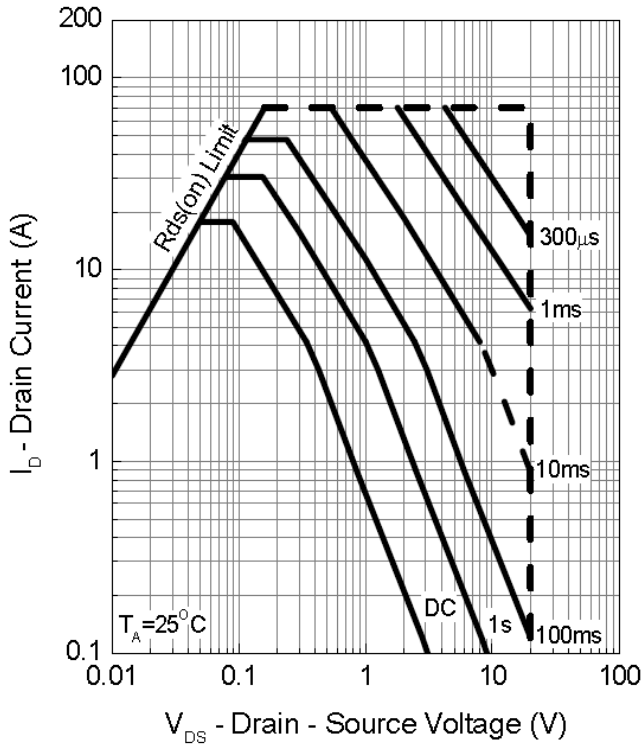


Thermal Transient Impedance

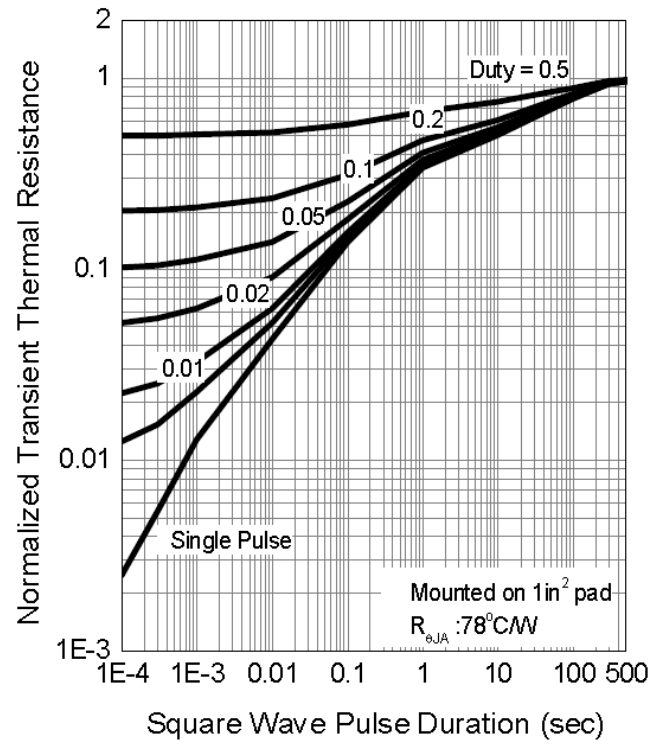


Typical Operating Characteristics(Cont.)

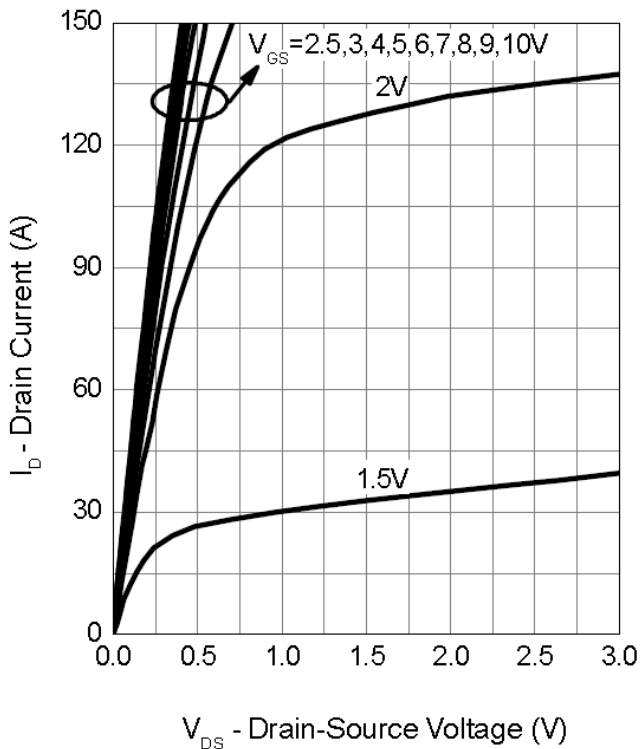
Safe Operation Area



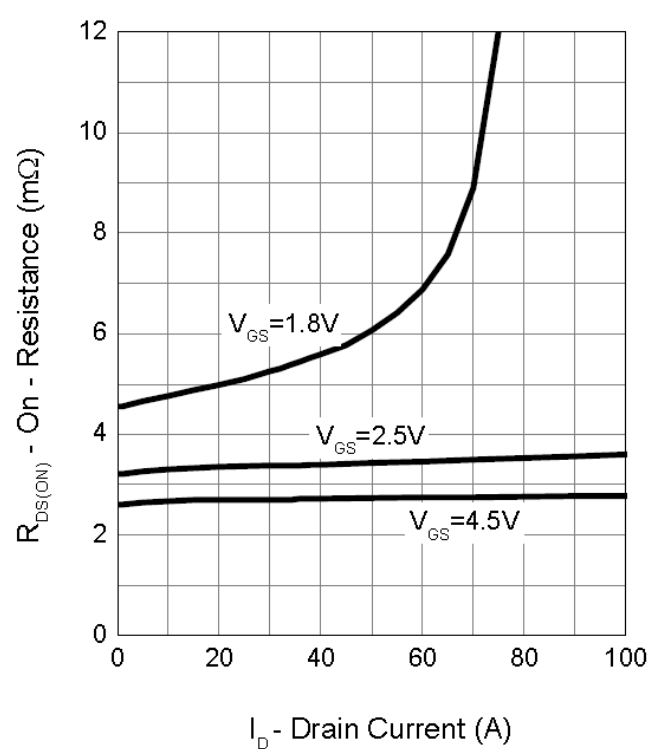
Thermal Transient Impedance



Output Characteristics

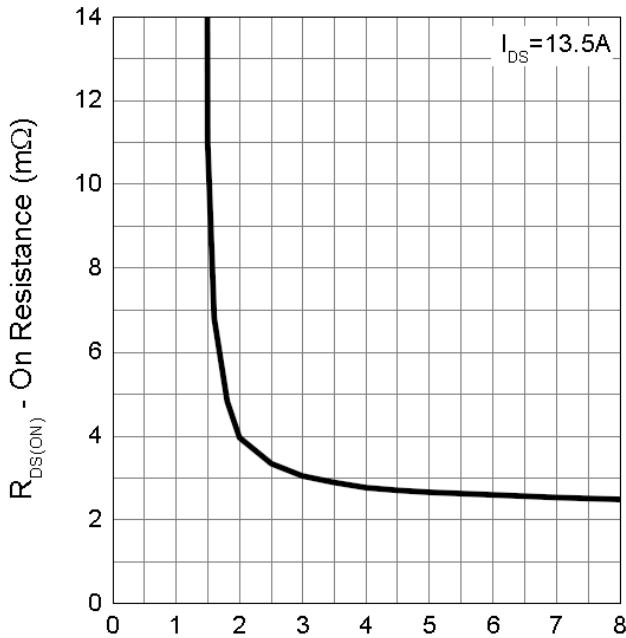


Drain-Source On Resistance



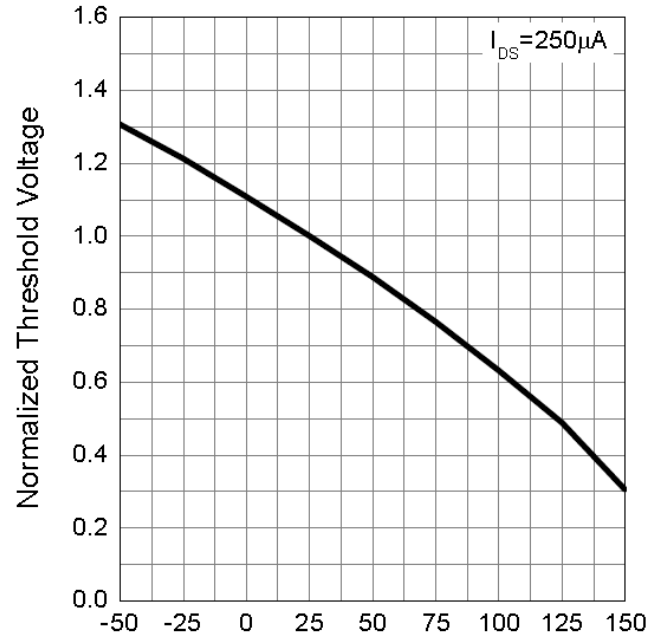
Typical Operating Characteristics (Cont.)

Gate-Source On Resistance

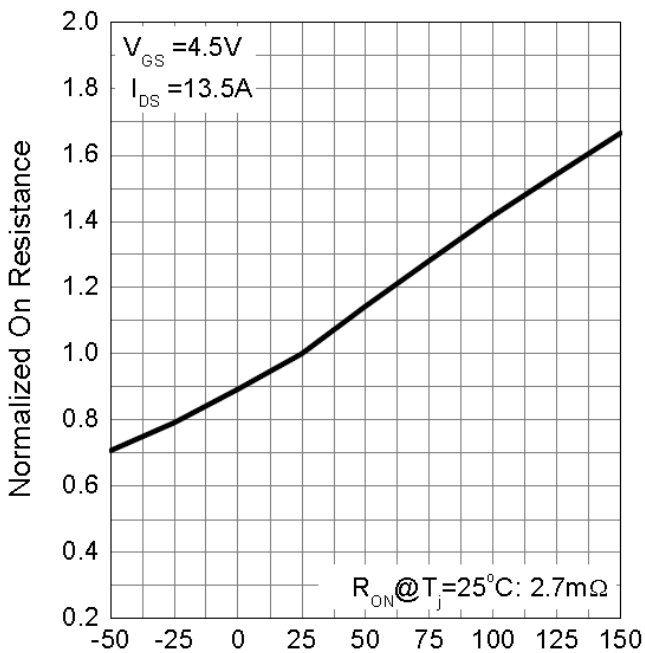


V_{GS} - Gate - Source Voltage (V)
Drain-Source On Resistance

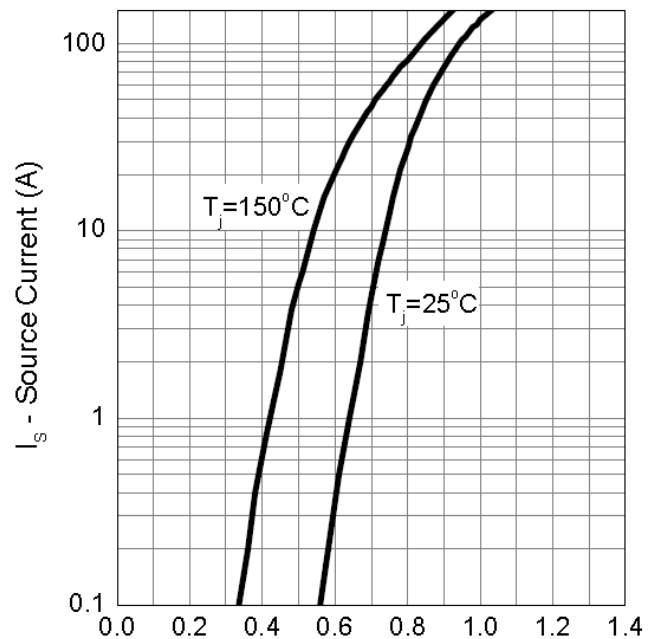
Gate Threshold Voltage



T_J - Junction Temperature (°C)
Source-Drain Diode Forward



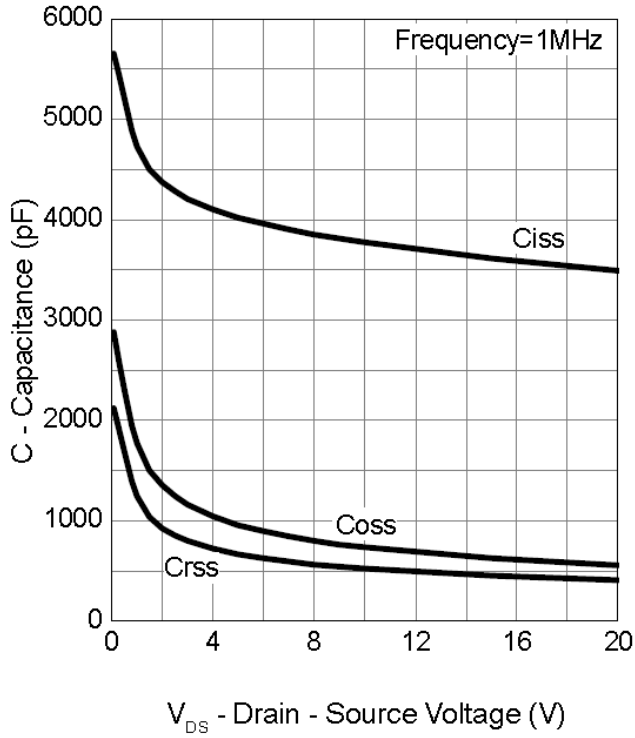
T_J - Junction Temperature (°C)



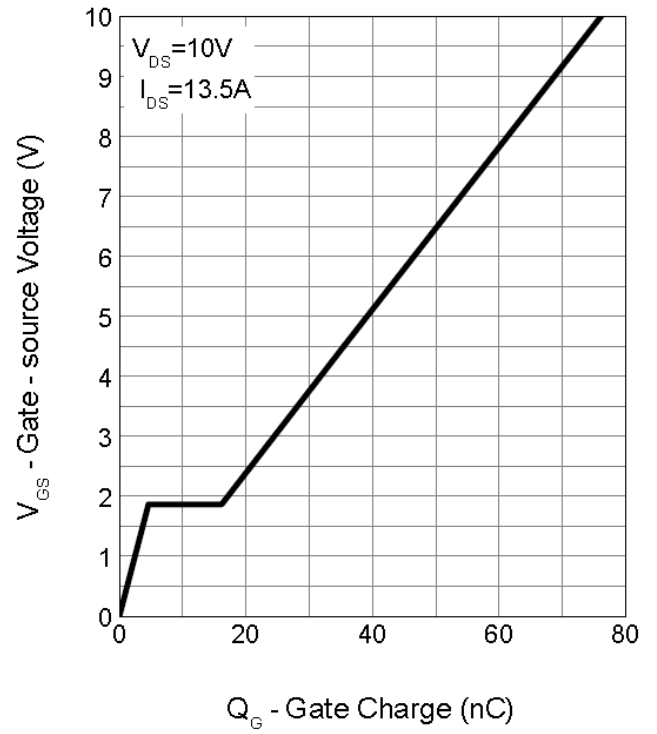
V_{SD} - Source - Drain Voltage (V)

Typical Operating Characteristics (Cont.)

Capacitance

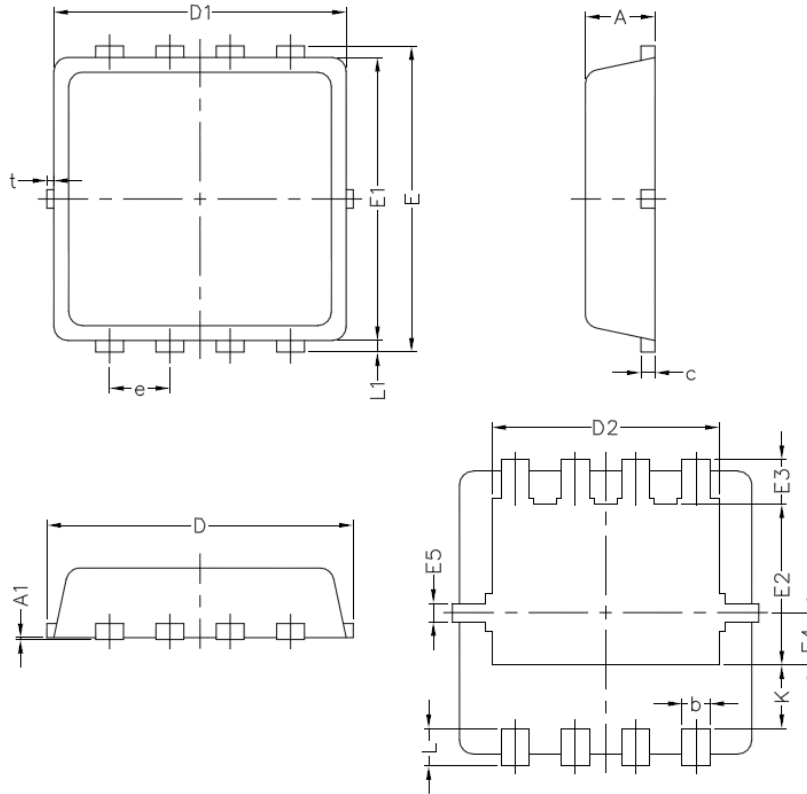


Gate Charge



Package Information

PPAK-3*3-8 Package



| Symbol | PPAK-3*3-8(mm) | | |
|--------|----------------|-------|------|
| | Min | Nom | Max |
| A | 0.70 | 0.75 | 0.85 |
| A1 | / | / | 0.05 |
| b | 0.20 | 0.30 | 0.40 |
| c | 0.10 | 0.152 | 0.25 |
| D | 3.15 | 3.3 | 3.45 |
| D1 | 3.00 | 3.15 | 3.30 |
| D2 | 2.25 | 2.45 | 2.65 |
| E | 3.15 | 3.30 | 3.45 |
| E1 | 2.90 | 3.05 | 3.20 |
| E2 | 1.54 | 1.74 | 1.94 |
| E3 | 0.28 | 0.48 | 0.68 |
| E4 | 0.37 | 0.57 | 0.77 |
| E5 | 0.10 | 0.20 | 0.30 |
| e | 0.60 | 0.65 | 0.70 |
| K | 0.49 | 0.69 | 0.89 |
| L | 0.30 | 0.40 | 0.50 |
| L1 | 0.06 | 0.125 | 0.20 |
| t | / | / | 0.13 |

Design Notes